



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20251211002.1

**Qualification of RFAB as an additional Fab site, Die change,
Datasheet change and BOM option for select devices
Change Notification / Sample Request**

Date: December 11, 2025

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251211002.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM5005MHX/NOPB	LM5005MHX/NOPB
LM5576MHX/NOPB	LM5576MHX/NOPB
LM25005MH/NOPB	LM25005MH/NOPB
LM5576MH/NOPB	LM5576MH/NOPB
LM25576MHX/NOPB	LM25576MHX/NOPB
LM5005MH/NOPB	LM5005MH/NOPB

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251211002.1		PCN Date:	December 11, 2025																			
Title:	Qualification of RFAB as an additional Fab site, Die change, Datasheet change and BOM option for select devices																						
Customer Contact:	Change Management Team		Dept:	Quality Services																			
Proposed 1st Ship Date:	March 11, 2026		Sample requests accepted until:	February 09, 2026*																			
*Sample requests received after February 09, 2026 will not be supported.																							
Change Type:																							
<input type="checkbox"/>	Assembly Site	<input checked="" type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material																		
<input checked="" type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process																		
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input checked="" type="checkbox"/>	Wafer Fab Site																		
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input checked="" type="checkbox"/>	Wafer Fab Material																		
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input checked="" type="checkbox"/>	Wafer Fab Process																		
PCN Details																							
Description of Change:																							
Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option, die change and BOM option for the devices listed below.																							
<table border="1"> <thead> <tr> <th colspan="3">Current Fab Site</th> <th colspan="3">Additional Fab site</th> </tr> <tr> <th>Current Fab Site</th> <th>Process</th> <th>Wafer Diameter</th> <th>Additional Fab site</th> <th>Process</th> <th>Wafer Diameter</th> </tr> </thead> <tbody> <tr> <td>MAINEFAB</td> <td>ABCD</td> <td>200mm</td> <td>RFAB</td> <td>LBC9</td> <td>300mm</td> </tr> </tbody> </table>						Current Fab Site			Additional Fab site			Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter	MAINEFAB	ABCD	200mm	RFAB	LBC9	300mm
Current Fab Site			Additional Fab site																				
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter																		
MAINEFAB	ABCD	200mm	RFAB	LBC9	300mm																		
The die was also changed as a result of the process change.																							
Construction differences as follows:																							
<table border="1"> <thead> <tr> <th></th> <th>Current</th> <th>Additional</th> </tr> </thead> <tbody> <tr> <td>Wire diam/type</td> <td>1.30mil Au/1.30mil Cu</td> <td>1.30mil Cu</td> </tr> <tr> <td>Mount compound</td> <td>8075531</td> <td>4211470</td> </tr> <tr> <td>Mold compound</td> <td>8095178</td> <td>4228573</td> </tr> </tbody> </table>							Current	Additional	Wire diam/type	1.30mil Au/1.30mil Cu	1.30mil Cu	Mount compound	8075531	4211470	Mold compound	8095178	4228573						
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Wire diam/type	1.30mil Au/1.30mil Cu	1.30mil Cu																					
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Mold compound	8095178	4228573																					
The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.																							



LM25005

SNVS411D – JANUARY 2006 – REVISED DECEMBER 2025

Changes from Revision C (March 2013) to Revision D (December 2025)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Added Applications section.....	1
• Moved Simplified Application Schematic to Description section.....	1
• Moved package information to Package Information table.....	1
• Changed section title from: Connection Diagram to: Pin Configuration and Functions.....	3
• Added ESD Ratings.....	5
• Changed from: Operating Ratings to: Recommended Operating Conditions.....	5
• Added Thermal Resistance Characteristics section.....	5
• Updated Bias Current (lin) from: 3mA to: 2mA.....	6
• Updated typical shutdown current from: 50µA to: 48µA.....	6
• Changed BOOST UVLO Hysteresis from 0.56V to 0.8V.....	6
• Changed FB Bias Current from 17nA to 10nA.....	6
• Changed from: Typical Performance Characteristics to: Typical Characteristics.....	8
• Updated from: Detailed Operating Description to: Overview.....	10
• Moved Functional Block Diagram to Detailed Description section.....	11
• Added Application and Implementation section.....	18
• Added Application Information section.....	18
• Added Typical Application section.....	19
• Added Design Requirements section.....	19
• Added Detailed Design Procedure section.....	19
• Added Application Curves section.....	25
• Added Power Supply Recommendations section.....	25
• Changed from: PCB LAYOUT AND THERMAL CONSIDERATIONS to: Layout Guidelines.....	25
• Moved PCB Layout figures to Layout Example section.....	27



LM5005
SNVS397F – SEPTEMBER 2005 – REVISED DECEMBER 2025

Changes from Revision E (November 2016) to Revision F (December 2025)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed legacy terminology throughout document from: master to: controller and from: slave to: peripheral.....	1
• Updated V_{CC} Current limit from: 20mA to: 25mA.....	6
• Updated V_{CC} UVLO threshold from: 6.35V to: 5.35V.....	6
• Updated V_{CC} Undervoltage Hysteresis from: 1V to: 0.25V.....	6
• Added typical Bias current, I_{IN} current information.....	6
• Updated bias current I_{IN} maximum current from: 5mA to: 4.5mA.....	6
• Updated typical shutdown current from: 60µA to: 48µA.....	6
• Updated maximum shutdown current from: 100µA to: 85µA.....	6
• Added Pre-charge Switch on time parameter.....	6
• Updated Buck Switch R_{ds_on} from: 160mΩ to: 170mΩ.....	6
• Updated BOOST UVLO Hysteresis from: 0.56V to: 0.8V.....	6
• Updated cycle by cycle current limit delay from: 100nsec to: 75nsec.....	6



LM25576
SNVS470I – JANUARY 2007 – REVISED NOVEMBER 2025

Changes from Revision H (August 2017) to Revision I (November 2025)	Page
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed all instances of legacy terminology to controller and peripheral.....	1
• Added Charged-device model spec to the <i>ESD Ratings</i> table.....	5
• Added the <i>Thermal Information</i> table.....	5
• Changed Bias Current (lin) from 3.4mA to 2mA.....	6
• Changed Shutdown Current (lin) from 57µA to 48µA.....	6
• Changed BOOST UVLO Hysteresis from 0.56V to 0.8V.....	6
• Changed FB Bias Current from 17nA to 10nA.....	6
• Changed the <i>External Components</i> section to the <i>Design Requirements</i> section.....	19
• Added the <i>Application Curves</i> section.....	24
• Added the <i>Power Supply Recommendations</i> section.....	24
• Added the <i>Power Dissipation</i> section.....	27
• Added the <i>Thermal Considerations</i> section.....	27

Changes from Revision J (October 2014) to Revision K (November 2025)
Page

• Deleted SIMPLE SWITCHER® branding from the data sheet.....	1
• Moved the automotive device to a standalone data sheet (SNOSB24).....	1
• Added WEBENCH links throughout the document.....	1
• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1
• Changed all instances of legacy terminology to controller and peripheral.....	1
• Updated Figure 4-1	3
• Moved the storage temperature information to the <i>Absolute Maximum Ratings</i> table.....	5
• Updated table note to the latest standards.....	5
• Added Charged-device model (CDM) spec to the <i>ESD Ratings</i> table.....	5
• Added the latest information to the <i>Thermal Information</i> table.....	5
• Changed Bias Current (lin) from 3.4mA to 2mA.....	6
• Changed Shutdown Current (lin) from 57uA to 48uA.....	6
• Changed BOOST UVLO Hysteresis from 0.56V to 0.8V.....	6
• Changed FB Bias Current from 17nA to 10nA.....	6
• Updated the <i>Power Supply Recommendations</i> section.....	26
• Added the <i>Power Dissipation</i> section.....	28
• Added the <i>Thermal Considerations</i> section.....	28

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
LM25005	SNVS411C	SNVS411D	http://www.ti.com/product/LM25005
LM5005	SNVS397E	SNVS397F	http://www.ti.com/product/LM5005
LM25576	SNVS470H	SNVS470I	http://www.ti.com/product/LM25576
LM5576	SNVS447J	SNVS447K	http://www.ti.com/product/LM5576

Qual details are provided in the Qual Data Section.

Reason for Change:

Supply Continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None, see the standard data package for reference

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS
☒ No Change

REACH
☒ No Change

Green Status
☒ No Change

IEC 62474
☒ No Change

Changes to product identification resulting from this PCN:
**Fab Site
Information:**

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MAINEFAB	CUA	USA	South Portland
RFAB	RFB	USA	Richardson

Die Rev:

Current	New
Die Rev [2P]	Die Rev [2P]
A, B	A

Sample product shipping label (not actual product label):

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0000017
 (20L) CS0: SHE (21L) CC0:USA
 (22L) AS0: MLA (23L) AC0: MYS

Product Affected:		
LM25005MH/NOPB	LM25576MHX/NOPB	LM5576MH/NOPB
LM25005MHX/NOPB	LM5005MH/NOPB	LM5576MHX/NOPB
LM25576MH/NOPB	LM5005MHX/NOPB	

Qualification Report

Approve Date 30-June-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: LM5576MH/NOPB	Qual Device: LM25576MH/NOPB	Qual Device: LM5005MH/NOPB	Qual Device: LM25005MH/NOPB	QBS Reference: BQ79600PWRQ1	QBS Reference: LM5576QMH/NOPB	QBS Reference: LM5576QMH/NOPB
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/231/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	3/135/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	3/231/0	1/77/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	3/2400/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	1/30/0	-
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	1/30/0	1/30/0	1/30/0	2/60/0	3/90/0	1/30/0
FTY	E6	Final Test Yield	-	-	1/1/0	-	1/1/0	-	-	-	1/1/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device LM5576MH/NOPB is qualified at MSL1 260C

Qual Device LM25576MH/NOPB is qualified at MSL1 260C

Qual Device LM5005MH/NOPB is qualified at MSL1 260C

Qual Device LM25005MH/NOPB is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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